

CLAIM AMENDMENTS

Claims 1-30 (Canceled).

31. (Currently Amended) A packaged integrated circuit device comprising:
a plurality of ~~gold-coated~~ solder ball bond pads, said solder ball bond pads
coupled to solder balls;
a plurality of ~~gold-coated~~ wire bond bond pads, said wire bond bond pads coupled
to bonding wires; and
a ~~the~~ gold coating on said solder ball bond pads and on said wire bond bond pads,
the gold coating on said solder ball bond pads being thinner than the gold coating on said wire
bond bond pads.

32. (Original) The device of claim 31 wherein the thickness of the gold on said
solder ball bond pads is sufficiently low to reduce the likelihood of solder ball joint
embrittlement.

33. (Currently Amended) The device of claim 31 wherein the gold coating on
said solder ball bond pads ~~have a gold-coating having~~ has a thickness of between about ~~+1~~ 0.1 and
0.3 ~~→~~ microns.

34. (Currently Amended) The device of claim 33 wherein the gold coating on
said solder ball bond ~~pads~~ pad ~~gold-coating~~ has a thickness of about ~~25~~ 0.25 microns.

35. (Currently Amended) The device of claim 33 wherein said the gold coating
on said wire bond bond pads has a ~~have a gold-coating~~ thickness of approximately ~~5~~ 0.5
microns.

36. (Original) The device of claim 31 wherein said solder ball bond pads and said
wire bond bond pads are all contained on the same planar surface.

37. (New) A device comprising:
a first and second bond pad, said first and second bond pads comprising a nickel coated metal; and

a gold coating on said first and second bond pads, the gold coating on said first bond pad thinner than the gold coating on said second bond pad.

38. (New) The device of claim 37 wherein the first bond pad comprises a nickel coated copper.

39. (New) The device of claim 38 wherein the second bond pad comprises a nickel coated aluminum.

40. (New) The device of claim 37 wherein the gold coating on said second bond pad is a composite of two different gold coatings.

41. (New) The device of claim 37 wherein the gold coating on the first bond pad has a thickness of between about 0.1 and 0.3 microns.

42. (New) The device of claim 37 wherein the gold coating on the second bond pad has a thickness of about 0.5 microns.

43. (New) The device of claim 37 wherein the first and second bond pads coexist on a planar support structure.

44. (New) An intermediate structure for an integrated circuit device comprising:
a first bond pad comprising a gold coated metal, said gold coating having a thickness of between about 0.1 and 0.5 microns; and
a second bond pad which is masked, said second bond pad comprising a nickel coated metal.

45. (New) The structure of claim 44 wherein the metal of said first bond pad comprises a nickel coated aluminum.

46. (New) The structure of claim 44 wherein said second bond pad comprises a nickel coated copper.

47. (New) The structure of claim 44 wherein said first and second bond pads are on the same planar surface.